

# FASTER CHEAPER BETTER

IKONICS PHOTO-MACHINING

CALL TODAY FOR  
FREE CONSULTATION.  
800-643-1037

**QUICK TURNAROUND:**  
DESIGN AND SAMPLES - 2 WEEKS

**MATERIALS:**  
GLASS, SILICON AND OTHER  
BRITTLE SUBSTRATES

**PRECISION:**  
< 25UM ON FEATURE SIZE AND DEPTH,  
WITHIN MICRONS ON POSITION

 **IKONICS®**  
INDUSTRIAL

## OVERVIEW

Photo-Machining combines the precision of photolithography using a proprietary photoresist system developed by IKONICS, and powder blasting to provide customers cost-effective alternative machining solutions and rapid turnaround (< 2 weeks). Photo-Machining excels in processing thin (75µm), fragile material, such as borosilicate or silicon structured wafers for MEMS and sensor packaging. Photo-Machining can produce a wide variety of blind and thru-features that are both detailed and deep (dependent on feature and aspect ratio). The process is ideally suited for large area removal and high pitch density. It can also accommodate large parts of 400mm (16") and greater. Services offered for both short run prototypes and high volume production.

## KEY FEATURES:

- Holes, blind vias, cavities, posts/mesas/pads, micro-grooves
- Thin Membranes/Diaphragms
- Large area removal
- All surfaces are fully protected throughout manufacturing process

## INDUSTRIES SERVED:

- MEMS / Sensors
- Semiconductor
- Aerospace
- Biomedical
- Structural Ceramics

## POSSIBLE APPLICATIONS:

- Wafer Level Packaging
- Pressure Sensors
- Accelerometer Sensors
- Gyroscope Sensors
- Bio-MEMS (Lab-On-Chip)
- SAW Device
- Susceptor
- Microfluidics



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